

WHAT IS CLAIMED IS:

1           1.     A die with text deposited upon the die using semiconductor processing  
2 techniques, the die comprising:

3                   a substrate which is cut from a wafer comprising a plurality of substrates;

4                   a first paragraph in contact with the substrate; and

5                   a second paragraph in contact with the substrate and aligned with the first  
6 paragraph in a column.

1           2.     The die with text deposited upon the die using semiconductor  
2 processing techniques of claim 1, wherein:

3                   the substrate is a semiconductor substrate; and

4                   text in the column is comprised of one or more of a metal, an oxide, a  
5 polysemiconductor and a photoresist.

1           3.     The die with text deposited upon the die using semiconductor  
2 processing techniques of claim 1, wherein the first and second paragraphs are comprised of a  
3 plurality of characters.

1           4.     The die with text deposited upon the die using semiconductor  
2 processing techniques of claim 3, wherein each of the plurality of characters is comprised of a  
3 plurality of primitives.

1           5.     The die with text deposited upon the die using semiconductor  
2 processing techniques of claim 1, the die further comprising:

3                   a first character appearing in a first color; and

4                   a second character appearing in a second color.

1           6.     The die with text deposited upon the die using semiconductor  
2 processing techniques of claim 1, the die further comprising an image on the substrate.

1           7.     A method for depositing a plurality of paragraphs of text on a substrate  
2 with semiconductor processing techniques, the method comprising:

3 reading a first paragraph from an electronic source;  
4 reading a second paragraph from the electronic source;  
5 positioning the first and second paragraphs into a column;  
6 generating an electronic file at least partially representative of the column; and  
7 imaging the substrate with the column, wherein the substrate is cut from a  
8 wafer having a plurality of substrates.

1 8. The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 7, wherein the  
3 imaging the substrate includes lithographing the substrate with a mask.

1 9. The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 7, the method further  
3 comprising:

4 converting a first character of the first paragraph into a first pattern;  
5 converting a second character of the first paragraph into a second pattern; and  
6 aligning the first and second characters on a line.

1 10. The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 7, wherein the  
3 substrate is a semiconductor wafer.

1 11. The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 7, the method further  
3 comprising determining an end of a first line in the first paragraph and beginning a second  
4 line.

1 12. The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 7, the method further  
3 comprising determining an end of the first paragraph and beginning the second paragraph on  
4 the next line of the column.

1                   13.     The method for depositing the plurality of paragraphs of text on the  
2     substrate with semiconductor processing techniques as recited in claim 7, the method further  
3     comprising detecting an end of a first column and depositing a next line in a second column.

1                   14.     The method for depositing the plurality of paragraphs of text on the  
2     substrate with semiconductor processing techniques as recited in claim 7, the method further  
3     comprising:

4                   determining a first color for a first character; and  
5                   determining a second color for a second character.

1                   15.     The method for depositing the plurality of paragraphs of text on the  
2     substrate with semiconductor processing techniques as recited in claim 7, wherein the  
3     generating the electronic file comprises overlaying a silhouette over at least part of the  
4     column.

1                   16.     A lithographing system for depositing a plurality of paragraphs on a  
2     substrate, the lithographing system comprising:  
3                   a radiation source;  
4                   the substrate; and  
5                   a mask generated from an electronic file, wherein:  
6                   the mask is between the radiation source and the substrate, and  
7                   the mask includes a first and second paragraphs arranged in a column.

1                   17.     The lithographing system for depositing the plurality of paragraphs on  
2     the substrate as recited in claim 16, wherein the electronic file comprises a plurality of  
3     elements corresponding to characters for the plurality of paragraphs.

1                   18.     The lithographing system for depositing the plurality of paragraphs on  
2     the substrate as recited in claim 17, wherein each character of the first and second paragraphs  
3     is comprised of a plurality of rectangles wherein one side of the rectangle is equal in size to  
4     the process resolution.

1                   19.     The lithographing system for depositing the plurality of paragraphs on  
2 the substrate as recited in claim 16, wherein the first and second paragraphs are separated by  
3 at least one of: a hard return, a tab and an enlarged character.

1                   20.     The lithographing system for depositing the plurality of paragraphs on  
2 the substrate as recited in claim 16, the lithographing system further comprising:

3                   a first character visible as a first color; and  
4                   a second character visible as a second color.

1                   21.     A method for depositing text and an image on a substrate with  
2 semiconductor processing techniques, the method comprising:

3                   loading a phrase;  
4                   loading a silhouette image;

5                   providing a mask file at least partially representative of the phrase and the  
6 silhouette image, wherein the generating step comprises overlaying a silhouette over at least  
7 part of the phrase; and

8                   imaging the substrate with the electronic file.

1                   22.     The method for depositing text and the image on the substrate with  
2 semiconductor processing techniques as recited in claim 21, wherein the imaging the  
3 substrate includes lithographing the substrate with a mask.

1                   23.     The method for depositing text and the image on the substrate with  
2 semiconductor processing techniques as recited in claim 21, the method further comprising:  
3                   converting a first character of the phrase into a first pattern;  
4                   converting a second character of the phrase into a second pattern; and  
5                   aligning the first and second characters on a line.

1                   24.     The method for depositing text and the image on the substrate with  
2 semiconductor processing techniques as recited in claim 21, wherein the substrate is a  
3 semiconductor wafer.

1                   25.    The method for depositing text and the image on the substrate with  
2 semiconductor processing techniques as recited in claim 21, the method further comprising:  
3                   determining a first color for a first character; and  
4                   determining a second color for a second character.

1                   26.    A method for depositing a plurality of paragraphs of text on a substrate  
2 with semiconductor processing techniques, the method comprising:  
3                   reading a first paragraph from an electronic source;  
4                   reading a second paragraph from the electronic source;  
5                   positioning the first and second paragraphs into one or more columns;  
6                   generating an electronic file at least partially representative of the column; and  
7                   producing the column on the substrate using semiconductor processing  
8 techniques, wherein the substrate is cut from a wafer having a plurality of substrates.

1                   27.    The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, wherein the  
3 producing step includes lithographing the substrate with a mask.

1                   28.    The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, the method further  
3 comprising:  
4                   converting a first character of the first paragraph into a first pattern;  
5                   converting a second character of the first paragraph into a second pattern; and  
6                   aligning the first and second characters on a line.

1                   29.    The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, wherein the  
3 substrate is a semiconductor wafer.

1                   30.    The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, the method further

3 comprising determining an end of a first line in the first paragraph and beginning a second  
4 line.

1                   31.       The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, the method further  
3 comprising determining an end of the first paragraph and beginning the second paragraph on  
4 the next line of the column.

1                   32.       The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, the method further  
3 comprising detecting an end of a first column and depositing a next line in a second column.

1                   33.       The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, the method further  
3 comprising:

4                   determining a first color for a first character; and  
5                   determining a second color for a second character.

1                   34.       The method for depositing the plurality of paragraphs of text on the  
2 substrate with semiconductor processing techniques as recited in claim 26, wherein the  
3 generating the electronic file comprises overlaying a silhouette over at least part of the  
4 column.